



Reliability Concerns for Flying SiC Power MOSFETs in Space

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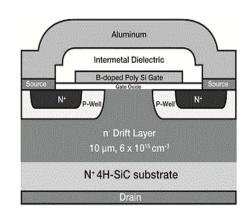
At Vanderbilt University: NASA Early Stage Innovation Grant No: NNX17AD09G

At NASA Goddard: NEPP Program

At University of Jyväskylä: ESA/ESTEC Contract No. 4000111630/14/NL/PA and Academy of Finland Project No. 2513553

Outline

- 1. Why the interest in SiC power?
- 2. Electrical reliability.
- 3. SEB in SiC power MOSFETs.
- 4. Environment.
- 5. Estimating failure rate in space.



1200 V SiC Power MOSFET

Why Silicon Carbide Power Devices for Space?

SiC vs Silicon Power Devices:

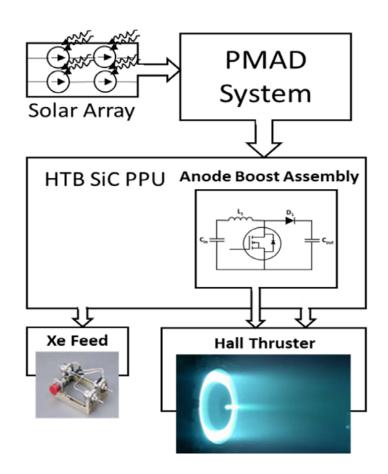
- Higher Breakdown Voltage (~ 10x vs. Si)
- Lower On-State Resistance (~1/100 vs. Si)
- Higher Temperature Operation (~3x vs. Si)
- High Thermal Conductivity (~10x vs. Si)
- Mass, cost, power savings

After: A. Elasser and T.P. Chow, Proc. IEEE, vol. 90, 2002.

Example: Concept Design of High Power Solar Electric Propulsion (SEP) for Human Exploration

- Desired power levels ~400 kW
- Change from 120 V bus voltage to 300 V

After: D.J. Hoffman, et al., NASA/TM—2011-217281



PMAD: Power management and distribution
HTB PPU: High-temperature boost power processing unit

Toyota and Denso Development for Hybrid Vehicles

- Power control units (PCUs) contain multiple power semiconductors
 usually silicon technology
- According to Toyota, ~20% of hybrid electric vehicle (HEV) total electrical power loss is associated with power semiconductors
- Goal to improve hybrid vehicle (HV) fuel efficiency by 10% and PCU downsizing of 80%
- SiC technology leads to lower weight, higher efficiency

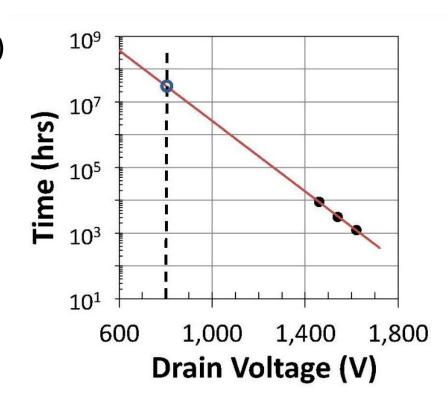


https://newsroom.toyota.co.jp/en/detail/2656842 (Image used with permission)

http://www.eenewseurope.com/design-center/potential-silicon-carbide-sic-automotive-applications/page/0/3

Accelerated Testing – High-Temperature Reverse Bias

- High-Temperature Reverse Bias (HTRB)
- Wolfspeed 1200 V 20A G2 MOSFETs
- V_{GS} = 0V, V_{DS} = 1460V, 1540V, 1620V
- Mean failure time at a given V_{DS} predicted by extrapolation
- At 800 V_{DS}, extrapolated failure time is ~ 3 x 10⁷ hours (~ 3400 years)

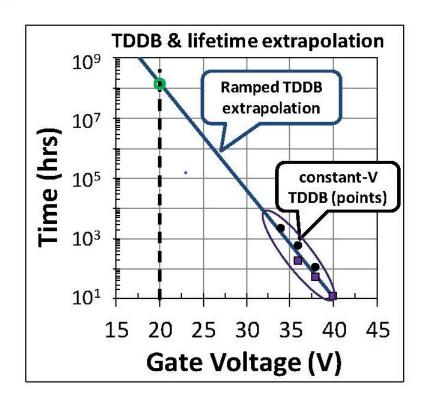


After: D.J. Lichtenwalner, B. Hull, J. Richmond, J. Casady, D. Grider, S. Allen, and J.W. Palmour, Wolfspeed – A CREE Company, presented at NASA Space Technology Mission Directorate Early Stage Innovation Technical Exchange, NASA GSFC, September 2017.

See: D.J. Lichtenwalner, et al., MRS Advances, vol.1, no. 2, pp. 81-89, 2016.

Accelerated Testing – Time-Dependent Dielectric Breakdown

- Time-Dependent Dielectric Breakdown (TDDB)
- Wolfspeed 1200 V 20A G2 MOSFETs
- Mean failure time at a given V_{GS} predicted by extrapolation
- Extrapolated mean failure time at
 V_{GS} > 10⁸ hours (~ 11,000 years)

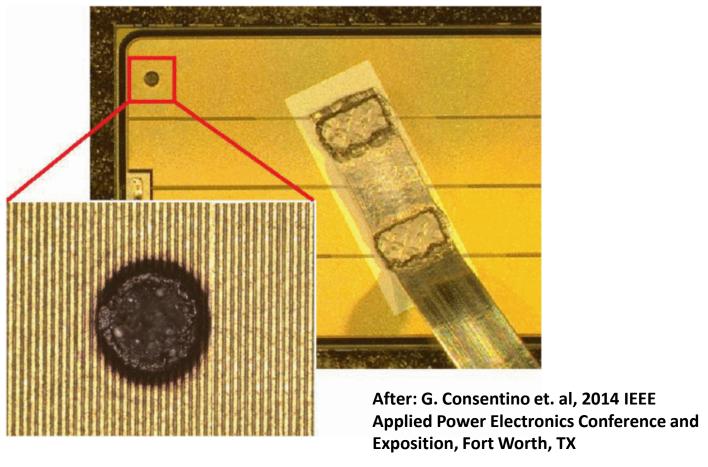


After: D.J. Lichtenwalner, B. Hull, J. Richmond, J. Casady, D. Grider, S. Allen, and J.W. Palmour, Wolfspeed – A CREE Company, presented at NASA Space Technology Mission Directorate Early Stage Innovation Technical Exchange, NASA GSFC, September 2017.

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What is the Problem?

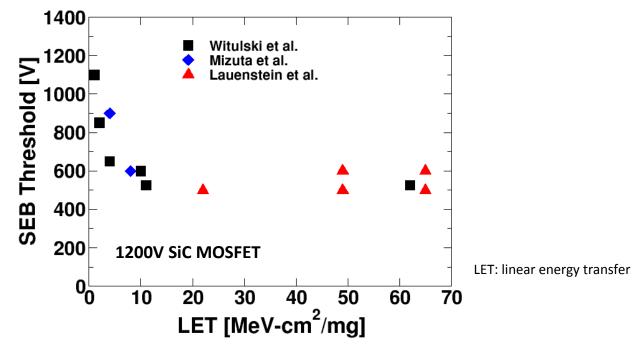
 SiC power devices – both diodes and MOSFETs – are susceptible to catastrophic failure in the swift, energetic heavy ion environment encountered in space or neutron environments



Measurement of SEB in SiC Power MOSFET

- Tests performed on SiC power devices rated 650 V to 3300 V by NASA, ESA, JAXA, and others
- Single-event burnout (SEB) occurs at typically ½ rated V_{DS}

 Ion-induced degradation observed in gate, drain leakage currents prior to SEB



Witulski, et al., RADECS 2017 and IEEE Trans. Nucl. Sci. (tbp). Mizuta, et al., IEEE Trans. Nucl. Sci., vol. 61, 2014. Lauenstein, et al., NASA Report GSFC-E-DAA-TN25023 (2015).

Lethal Ion Criteria

- Most particles in space are of no consequence to MOSFET catastrophic failure.
- To be lethal, a particle (or one of its recoils), must:
 - 1. Have sufficient energy deposition
 - 2. Strike at the proper solid angle
 - 3. Strike within the sensitive area
 - 4. Strike when the biases are in a critical state

After: J.L. Titus et. al, IEEE Trans. Nucl. Sci., vol. 46, 1999.

Estimate of the Failure Rate for 1200 V SiC Power MOSFETs in Space

- Devices show SEB failure at ≈ 500 V for LET > 10 MeV-cm²/mg
- Assume SEB cross-section saturated for LET > 10 MeV-cm²/mg
- Define SEB failure as operation at a reverse voltage > 500 V for any LET > 10

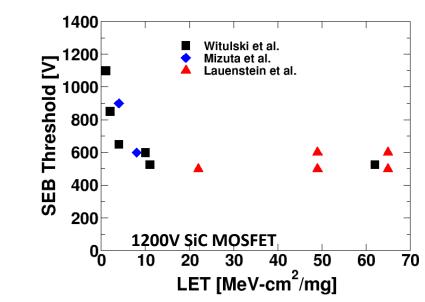
Failure Rate (FR) = SEB cross-section (σ) \int Flux(LET) dLET

Flux(LET) dLET = integral over LET spectrum for LETs greater than 10 MeV-cm²/mg using CREME96 or Xapsos et al.

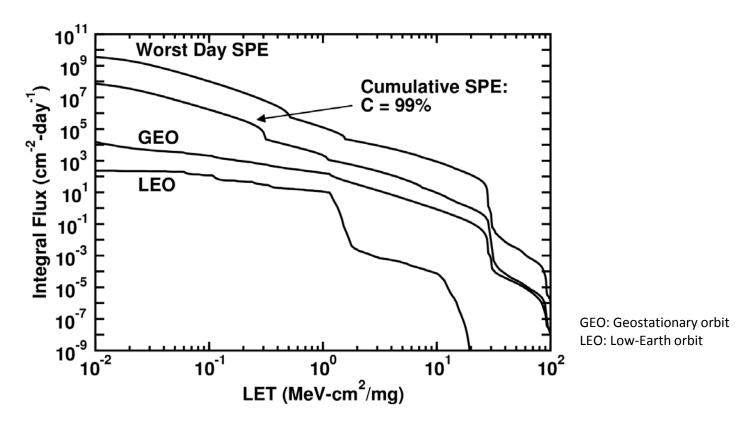
After: E. Dashdondog *et al.*, Microelectronics Reliability, vol. 84, 2016.

similar to

J.L. Titus *et al.,* IEEE Trans. Nucl. Sci., vol. 46,1999. J-M. Lauenstein *et al.,* IEEE Trans. Nucl. Sci., vol. 58, 2011.



Integral LET Spectra



Worst day solar particle event (SPE) from CREME96. GEO and LEO are solar minimum spectra from CREME96. Cumulative solar particle event spectra at the 99% confidence level after Xapsos *et al.* Results for 100 mils aluminum shielding.

See: M.A. Xapsos, C. Stauffer, T. Jordan, J.L. Barth, and R.A. Mewaldt, IEEE Trans. Nucl. Sci., vol. 64, 2007.

Worst Case Estimate of the Failure Rate (FR) for 1200 V SiC Power MOSFETs in Space

$$FR = \sigma \int Flux(LET) dLET$$

 σ = base MOSFET SEB cross-section on chip area, 1200V chip is ≈ 2 mm x 3 mm assume 50% sensitive area and 50% duty cycle

$$\sigma = 1.5 \times 10^{-2} \text{ cm}^2$$

Integral evaluated for all LET> 10 MeV-cm²/mg from the 99% confidence level curve from Xapsos *et al.* – appropriate a conservative design estimate of the single-event rate due to solar particles

$$\int Flux(LET) dLET = 10 cm-2 day-1$$

 $FR = 6.25 \times 10^{-3} / hour$ and $FIT = 6.25 \times 10^{6}$

MTTF (Mean Time To Failure) = 160 hours

Integral LET > 10 MeV-cm²/mg, FIT, MTTF for Different Mission and Satellite Scenarios

	Integral (no./cm²-day)	FIT (1 per billion hours)	MTTF (hours)
SPEW	1000	6.25E+08	1.6
SPE	10	6.25E+06	160
GEO	0.9	5.6E+05	1786
LEO	1E-04	62.5	1.6E+07

SPEW = worst day solar particle event from CREME96

SPE = cumulative particle event at 99% confidence level from Xapsos et al.

GEO = geostationary orbit during solar min from CREME96 LEO = low Earth orbit during solar min from CREME96 For all, 100 mils of aluminum shielding assumed.

FIT: Failure in time

MTTF on Orbit – 1200 V SiC MOSFET Operated at V_{DS} > 500 V

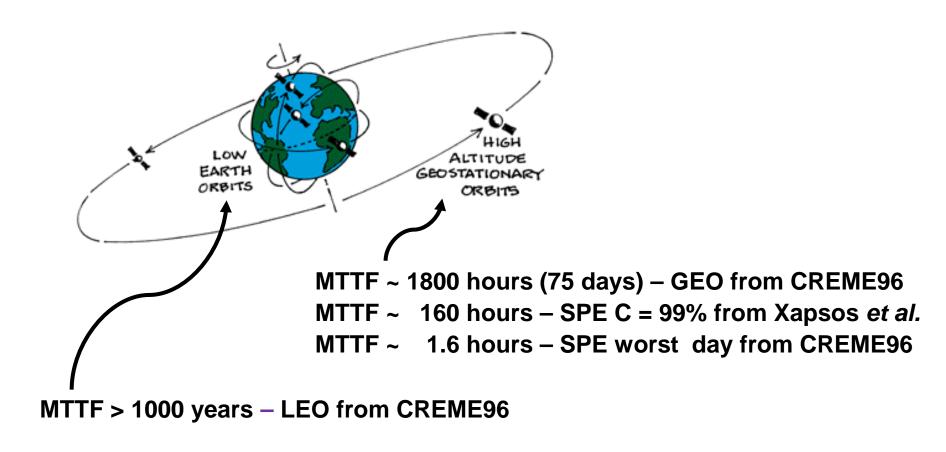


Image from: National Oceanic and Atmospheric Administration

Summary

- SiC power MOSFETs have several performance advantages over Si power MOSFETs and silicon IGBTs
- Current commercial devices are very reliable
- Demonstrated heavy-ion susceptibility
- Failure rate estimates indicate a radiation reliability issue for space electronics
- Any application of commercially available 1200 V SiC MOSFETs in space would require significant voltage de-rating
- Performance advantages may justify use if de-rating and leakage degradation is acceptable
- Careful heavy ion testing of any commercially available SiC MOSFET component proposed for spaceborne electronic systems is recommended





